

1024 - BIT STATIC RANDOM ACCESS MEMORY

- POWER SUPPLY $V_{CC} = 5V$
- TTL COMPATIBLE ALL INPUTS AND OUTPUTS
- THREE-STATE OUTPUT
- INPUTS PROTECTED AGAINST STATIC CHARGE
- ORGANIZATION 1024×1 BIT IN 16 PIN STD PACKAGE

TYPE	STANDBY PWR (mW)	OPERATING PWR (mW)	ACCESS TIME (ns)
M 2102 AL - 2	42	342	250
M 2102 AL	35	174	350
M 2102 AL - 4	35	174	450
M 2102 A - 2	—	342	250
M 2102 A	—	289	350
M 2102 A - 4	—	289	450
M 2102 A - 6	—	289	650

The M 2102A is a high speed 1024 word by 1 static N-channel silicon-gate MOS RAM. The device is fully static and therefore does not require clocks or refreshing to operate. The data is read out non destructively and has the same polarity as the input data.

A low standby power version (M 2102 AL) is also available. It has all the same operating characteristics of the M 2102A with the added feature of 35 mW maximum power dissipation in standby and 174 mW in operations. The device is available in 16 lead dual in-line ceramic package, metal-seal or frit-seal and plastic package.

ABSOLUTE MAXIMUM RATINGS

V_i^*	Input voltage (at any pin)	-0.5 to 7	V
P_{tot}	Total power dissipation	1	W
T_{stg}	Storage temperature	-65 to 150	°C
T_{op}	Operating temperature under bias	0 to 70	°C

* All voltage are referred to GND pin voltage

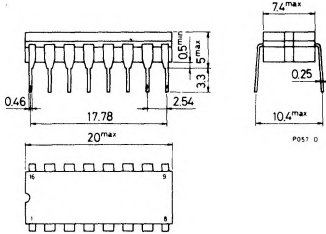
ORDERING NUMBERS: M 2102A - B1 for dual-in-line plastic package
M 2102A - D1 for dual-in-line ceramic package, metal-seal
M 2102A - F1 for dual-in-line ceramic package, frit-seal
M 2102AL - B1 for dual-in-line plastic package
M 2102AL - D1 for dual-in-line ceramic package, metal-seal
M 2102AL - F1 for dual-in-line ceramic package, frit-seal



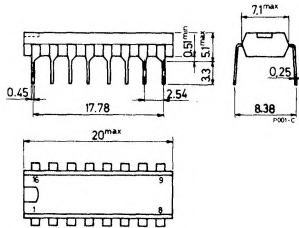
M 2102A
M 2102AL

MECHANICAL DATA (dimensions in mm)

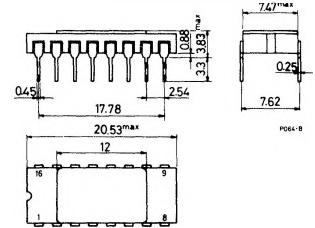
Dual in-line ceramic package
frit-seal for M2102A/AL-F1



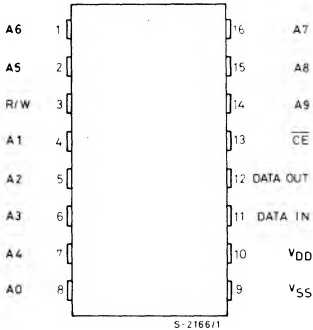
Dual in-line plastic package
for M 2102A/AL-B1



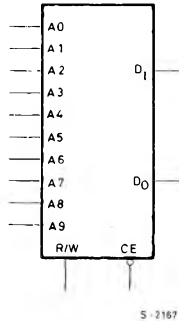
Dual in-line ceramic package
metal-seal for M 2102A/AL-D1



PIN CONNECTIONS



LOGIC DIAGRAM



PIN NAMES

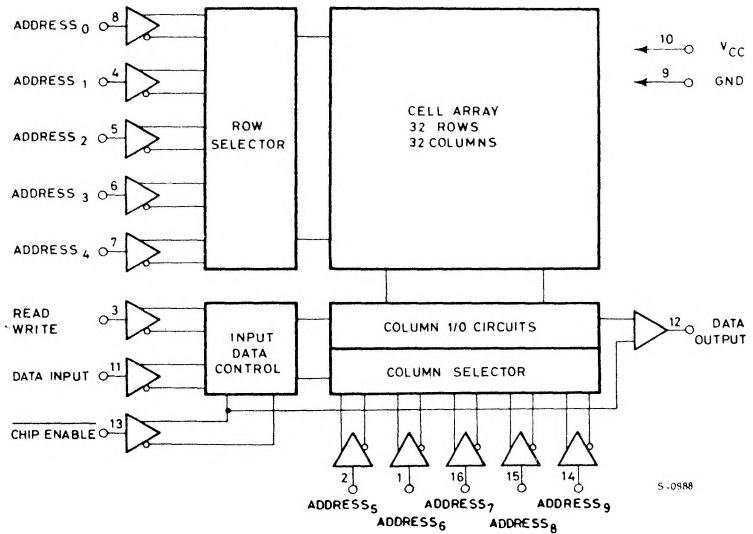
D _{IN}	DATA INPUT
A ₀ -A ₉	ADDRESS INPUTS
R/W	READ/WRITE INPUT
CE	CHIP ENABLE
D _{OUT}	DATA OUTPUT
V _{DD}	POWER (+5V)

TRUTH TABLE

CE	R/W	D _{IN}	D _{OUT}	MODE
H	X	X	HIGH Z	NOT SELECTED
L	L	L	L	WRITE "0"
L	L	H	H	WRITE "1"
L	H	X	D _{OUT}	READ



BLOCK DIAGRAM



STATIC ELECTRICAL CHARACTERISTICS (V_{CC} = 4.75 to 5.25V, T_{amb} = 0 to 70°C unless otherwise specified)

Parameter	Test conditions	M 2102 A M 2102 AL M 2102 A -4 M 2102 AL-4			M 2102 A -2 M 2102 AL-2			M 2102 A-6			Unit
		Min.	Typ.*	Max.	Min.	Typ.*	Max.	Min.	Typ.*	Max.	
V _{IH} Input high voltage		2		V _{CC}	2		V _{CC}	2.2		V _{CC}	V
V _{IL} Input low voltage		-0.5		0.8	-0.5		0.8	-0.5		0.65	V
V _{OH} Output high voltage	I _{OH} = -100 μA	2.4			2.4			2.2			V
V _{OL} Output low voltage	I _{OL} = 2.1 mA			0.4			0.4			0.45	V
I _{LI} Input load current	V _I = 0 to 5.25V		1	10		1	10		1	10	μA
I _{OH} Output leakage current	CE = 2V, V _O = V _{OH}		1	5		1	5		1	5	μA
I _{OL} Output leakage current	CE = 2V, V _O = 0.4V		-1	-10		-1	-10		-1	-10	μA
I _{CC} Supply current	V _I = 5.25V T _{amb} = 0°C Data out open		33	**		45	65		33	55	mA

* Typical values for T_{amb} = 25°C and nominal supply voltage.
 ** The maximum I_{CC} value is 55 mA for the M 2102A and M 2102A-4, and 33 mA for the M 2102AL and M 2102AL-4.



M 2102A
M 2102AL

DYNAMIC ELECTRICAL CHARACTERISTICS ($T_{amb} = 0$ to 70°C , $V_{CC} = 5\text{V} \pm 5\%$ unless otherwise specified)

Parameter	Test condition	M 2102 A -2 M 2102 AL-2		M 2102 A - M 2102 AL		M 2102 A -4 M 2102 AL-4		M 2102 A-6		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Read Cycle										
t_{rc}	Read cycle	250		350		450		650		ns
t_a	Access time		250		350		450		650	ns
t_E	CE to output time		130		180		230		400	ns
t_{OH1}	Previous read data valid with respect to address	40		40		40		50		ns
t_{OH2}	Previous read data valid with respect to chip enable	0		0		0		0		ns
$t_R, t_F = 10$ ns Load = 1 TTL gate and $C_L = 100$ pF										
Write Cycle										
t_{WC}	Write cycle	250		350		450		650		ns
t_{AW}	Address to with setup time	20		20		20		200		ns
t_{WP}	Write pulse width	180		250		300		400		ns
t_{WR}	Write recovery time	0		0		0		50		ns
t_S	Data setup time	180		250		300		450		ns
t_h	Data hold time	0		0		0		20		ns
t_{CW}	Chip enable to write setup time	180		250		300		550		ns
$t_R, t_F = 10$ ns Load = 1 TTL gate and $C_L = 100$ pF										

CAPACITANCES ($T_{amb} = 25^{\circ}\text{C}$, $f = 1$ MHz)

Parameter	Test conditions	Values			Unit	
		Min.	Typ.	Max.		
C_i	Input capacitance	$V_i = 0\text{V}$		3	5	pF
C_o	Output capacitance	$V_o = 0\text{V}$		7	10	pF



STANDBY CHARACTERISTICS ($T_{amb} = 0^{\circ}\text{C}$ to 70°C)

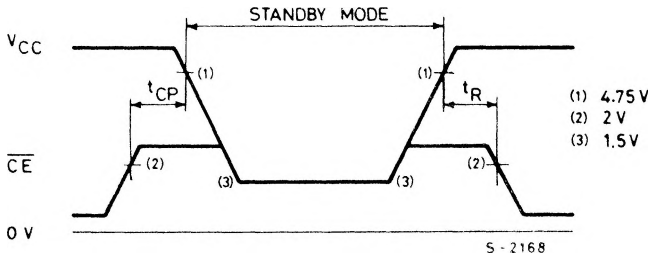
Parameter	Test conditions	M 2102 AL-4 M 2102 AL			M 2102 AL-2			Unit			
		Min.	Typ.*	Max.	Min.	Typ.*	Max.				
V_{PD}	V_{CC} in standby	1.5			1.5			V			
V_{CES}^{**}	CE bias in standby	$2V \leq V_{PD} \leq V_{CC} \text{ Max.}$			2			2	V		
		$1.5V \leq V_{PD} < 2V$			V_{PD}			V_{PD}	V		
I_{PD1}	Standby current	All inputs = $V_{PD1} = 1.5V$			15	23		20	28	mA	
I_{PD2}	Standby current	All inputs = $V_{PD2} = 2V$				20	30		25	38	mA
t_{CP}	Chip deselect to standby time		0				0			ns	
t_R^{***}	Standby recovery time		t_{RC}				t_{RC}			ns	

* Typical values are for $T_{amb} = 25^{\circ}\text{C}$.

** Consider the test conditions as shown: if the standby voltage (V_{PD}) is between 5.25V (V_{CC} max) and 2V, then \overline{CE} must be held at 2V Min. (V_{IH}). If the standby voltage is than 2V but greater than 1.5V (V_{PD} min), then \overline{CE} and standby voltage must be at least the same value or, if they are different, \overline{CE} must be the more positive of the two.

*** $t_R = t_{RC}$ (READ CYCLE TIME).

STANDBY WAVEFORMS

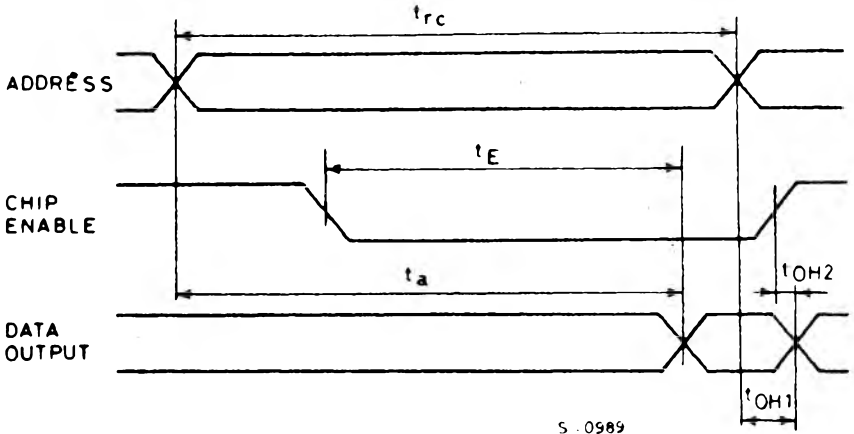




M 2102A
M 2102AL

WAVEFORMS

Read cycle



Write cycle

